



Material Content Data Sheet



Sales Product Name		BTS5014SDA		Issued		19. January 2018		
MA#		MA001081234						
Package		PG-TO252-5-11		Weight*		356.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.876	1.37	1.37	13665	13665
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		573	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	copper	7440-50-8	204.243	57.22	57.30	572379	573127
wire	non noble metal	aluminium	7429-90-5	1.170	0.33	0.33	3279	3279
encapsulation	organic material	carbon black	1333-86-4	1.380	0.39		3866	
	plastics	epoxy resin	-	24.143	6.77		67659	
	inorganic material	silicondioxide	60676-86-0	112.436	31.51	38.67	315097	386622
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14215	14215
plating	non noble metal	nickel	7440-02-0	0.076	0.02		214	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	215
glue	plastics	Polyimide	26023-21-2	0.143	0.04	0.04	400	400
solder	noble metal	silver	7440-22-4	0.076	0.02		212	
	non noble metal	tin	7440-31-5	0.060	0.02		170	
	non noble metal	lead	7439-92-1	2.889	0.81	0.85	8095	8477
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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